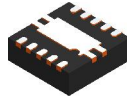


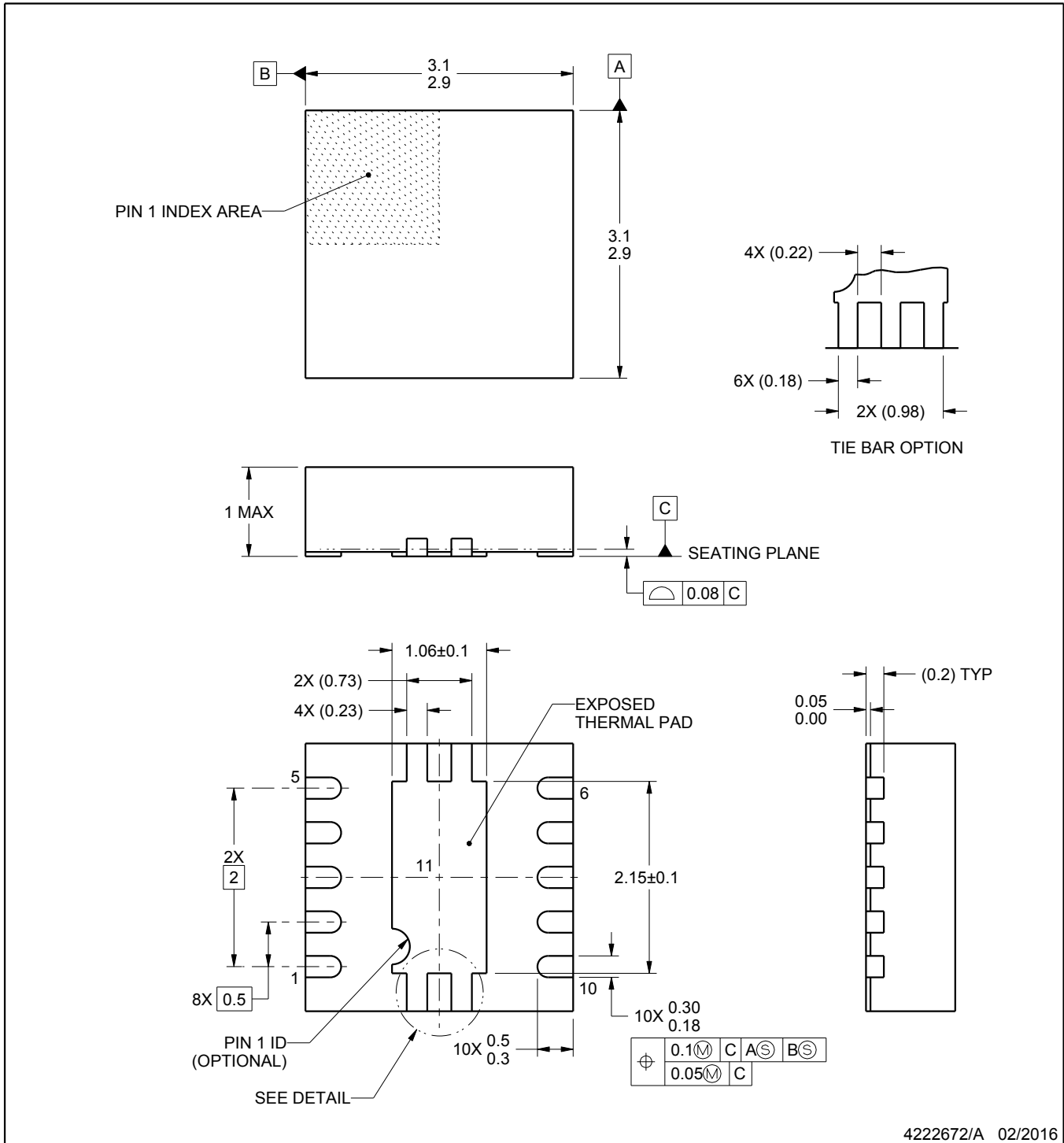
# DRC0010M



# PACKAGE OUTLINE

## VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222672/A 02/2016

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.





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